

## **Excellent Integrated System Limited**

Stocking Distributor

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[MG Chemicals](#)  
[8610-60G](#)

For any questions, you can email us directly:

[sales@integrated-circuit.com](mailto:sales@integrated-circuit.com)

## Non-Silicone Heat Transfer Compound



**8610**

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- Special synthetic base, fortified with metal oxides and compounded to a paste-like consistency for ease of application
- High efficient thermal conductive properties
  - Means more rapid transfer of heat for longer component life
- High temperature stability
  - Provides physical properties of low bleed and low evaporation for long-term service in any application that requires Heat Sink Compound.
- Uses synthetic fluids and metal oxide fillers
  - Provides excellent conductive properties that exceed those of other heat sink formulas
- Will not dry, harden, melt or migrate in any heat sink application
- Compatible with metal and plastic components
- Also available in a [silicone version](#)

### Benefits of Non Silicone Heat Transfer Compound OVER Silicone

No migration and component contamination.

#### Applications

- Typically, Heat Transfer Compounds (heat sink compounds) are used in OEM Electronic Component Plants to insure fast, accurate heat transfer in electronic components and circuitry
- Other used:
  - Semiconductor Mounting Devices
  - Thermal joints
  - Ballast heat transfer mediums
  - Power resistor mountings
  - Thermocouple wells
  - Transistor diodes & silicone rectifier base and mounting studs
  - ALL electric and electronic devices where efficient heat transfer cooling through thermal coupling is required

### Specifications

Physical Properties	Test Method	<a href="#">Non Silicone 8610</a>	<a href="#">Silicone 860</a>
Appearance	Visual	Off white / smooth paste	White paste
Consistency	ASTM D 217	310-320	
Specific Gravity @ 25°C (77°F)		2.5 min	2.3 min
Bleed % 24 hours @ 200°C	FTM-321	1.0% max	2.0% max
Evaporation 24 hours @ 200°C	FTM-321	2.0% max	2.0% max
Dropping Point	ASTM D-566	> 500°F (260°C)	> 500°F (260°C)
Min. operating temp.		-40°F/-40°F	55°F/48°C
Max. operating temp.		200°C	200°C (consistent) 300°C (intermittent)



## Heat Transfer Compounds

Electrical Properties	Test Method	<u>Non Silicone</u> <b>8610</b>	<u>Silicone</u> <b>860</b>
Thermal Conductivity	Hot Wire Method Heat Flow #36 °C	0.773 W/m•K	0.657 W/m•K
Dielectric Strength (0.051 gap)	ASTM D-149	350 V/MIL	400 V/MIL
Dielectric Constant @ 1000 Hz	ASTM D- 150	4.4	3.81
Dissipation Factor @ 1000 Hz	ASTM D 150	0.0021	0.0032
Resistivity @ 21°C	ASTM D 150	$6.38 \times 10^{13}$ Ohm•cm	$1.5 \times 10^{15}$ Ohm•cm

## Available Sizes

Catalog Number	Sizes Available	Description
8610-60G	60g (2 oz)	Liquid - TUBE
8610-1P	1 pint (2.5 lbs)	Tub